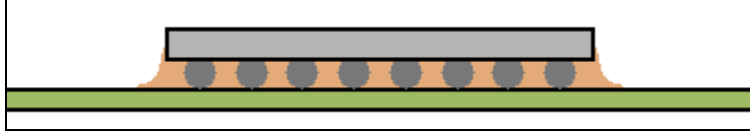


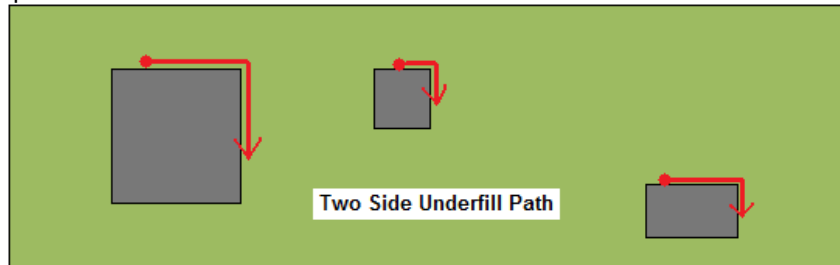
Methods, Target Conditions

Underfill Target Condition: BGA underfill should completely fill the space beneath the BGA components and leave a continuous fillet around the perimeter of the BGA device, that reaches from the PCB surface up to the bottom edge of the BGA device.



2 Side Underfill Method: Underfill is dispensed along two consecutive sides in one continuous pass. This may be repeated a number of times depending upon the size of the BGA to be under filled.

Do not allow the underfill material to be pulled completely beneath the BGA before replenishing the dispense path.



Check sides opposite the dispense lines for evidence of underfill beneath the device. When the underfill begins to appear on the opposite side of the dispensing, prepare to terminate the underfill dispense.